

List of claims (replacing prior versions).

1-33. (Cancelled)

34. (Currently Amended) A method of forming an electrical contact comprising:
assembling a panel ~~including a substrate~~, the panel having a printed circuit board having
planar surfaces and one or more electrical components mounted on one or more of the planar
surfaces, the panel having one or more conductive features enclosed within the panel and
unexposed to an exterior surface of the panel, the one or more conductive features being located
along a cut line;

cutting the panel along the cut line exposing portions of the one or more conductive
features for use as electrical connections to the printed circuit board ~~substrate~~; and

treating the portions of the one or more conductive features exposed from the cutting for
preservation as electrical connections.

35. (Original) The method of claim 34 wherein the treating further comprises
applying solder to the portions of the one or more conductive features exposed from the cutting.

36. (Original) The method of claim 34 wherein the treating further comprises
applying a conformal coating to the portions of the one or more conductive features exposed
from the cutting to protect against oxidation.

37. (Original) The method of claim 34 wherein the treating further comprises
applying a metal layer to the portions of the one or more conductive features exposed from the
cutting.

38. (Previously Presented) The method of claim 34 wherein the treating further
comprises attaching a lead of an adapter to the portions of the one or more conductive features
exposed from the cutting.

39. (Currently Amended) The method of claim 34 further comprising covering at least one surface of the printed circuit board substrate in an area including the cut line and the conductive features prior to cutting the printed circuit board substrate.

40. (Currently Amended) The method of claim 39 wherein the covering comprises encapsulating the printed circuit board substrate with a molding compound; and further comprising:

providing a registration feature having a predetermined relationship to the printed circuit board substrate, and

using the registration feature to align the cutting relative to the cut line.

41. (Currently Amended) The method of claim 34 further comprising establishing a pattern including at least one conductive layer in the substrate printed circuit board along the cut line to form the conductive features.

42. (Currently Amended) The method of claim 41 wherein the substrate printed circuit board comprises a multilayer printed circuit board and the establishing a pattern includes establishing a plurality of conductive layers along the cut line to form the conductive features.

43. (Currently Amended) The method of claim 34 further comprising establishing a pattern including at least one conductive via in the substrate printed circuit board along the cut line to form the conductive features.

44. (Original) The method of claim 43 wherein the conductive via is filled with a conductive material.

45. (Currently Amended) The method of claim 43 wherein the conductive via is buried in the printed circuit board substrate.

46. (Currently Amended) The method of claim 43 wherein the conductive via is a through hole contacting the surfaces of the printed circuit board ~~substrate~~.

47. (Original) The method of claim 46 wherein the through hole is filled with a conductive material.

48. (Currently Amended) The method of claim 34 wherein the conductive features are covered at the surfaces of the printed circuit board ~~substrate~~ by an insulation layer.

Claims 49-145 (Cancelled)

146. (Previously Presented) The method of claim 38 wherein the attaching further comprises soldering.

147. (Previously Presented) The method of claim 34 further comprising providing an adapter having one or more electrical terminals and wherein the treating comprises attaching the one or more electrical terminals to the portions of the one or more conductive features exposed from the cutting.

148. (Currently Amended) The method of claim 34 wherein ~~the substrate comprises a printed circuit board having planar surfaces, and~~ the assembling further comprises encapsulating the planar surfaces of the printed circuit board.

149. (Previously Presented) The method of claim 148 wherein the assembling further comprises forming a plurality of circuits on the printed circuit board and the cutting further comprises separating the plurality of circuits from the panel.

150. (Previously Presented) The method of claim 149 wherein at least one of the conductive features is positioned along a cutline between two adjacent circuits of the plurality of circuits.

151. (Previously Presented) The method of claim 150 wherein the at least one conductive feature is electrically connected to each of the two adjacent circuits, the cutting leaves a respective portion of the at least one conductive feature exposed in each of the two adjacent circuits to form a respective electrical connection.

152. (Previously Presented) The method of claim 149 further comprising attaching an electrically conductive member to selected ones of the exposed portions.

153. (New) A method of forming an electrical contact comprising:
assembling a panel including a substrate having one or more conductive features enclosed within the panel and unexposed to an exterior surface of the panel, the one or more conductive features being located along a cut line;
cutting the panel along the cut line exposing portions of the one or more conductive features for use as electrical connections to the substrate; and
treating the portions of the one or more conductive features exposed from the cutting for preservation as electrical connections;
wherein the substrate comprises a printed circuit board having planar surfaces, and the assembling further comprises encapsulating the planar surfaces of the printed circuit board;
wherein the assembling further comprises forming a plurality of circuits on the printed circuit board and the cutting further comprises separating the plurality of circuits from the panel.

154. (New) The method of claim 153 wherein at least one of the conductive features is positioned along a cutline between two adjacent circuits of the plurality of circuits.

155. (New) The method of claim 154 wherein the at least one conductive feature is electrically connected to each of the two adjacent circuits, the cutting leaves a respective portion of the at least one conductive feature exposed in each of the two adjacent circuits to form a respective electrical connection.

156. (New) The method of claim 153 further comprising attaching an electrically conductive member to selected ones of the exposed portions.